

S/N 09/382,524

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Paul A. Farrar

Examiner: Fetsum Abraham

Serial No.: 09/382,524

Group Art Unit: 2826

Filed: August 25, 1999

Docket: 303.610US1

Title: INSULATORS FOR HIGH DENSITY CIRCUITS

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Commissioner for Patents
Washington, D.C. 20231

Applicant has reviewed the Office action mailed on July 16, 2001. Please amend the above-identified patent application as follows.

IN THE CLAIMS

Please add the following new claims.

42. (New) An conductive system comprising:
a substrate;
a foamed material layer on the substrate, the foamed material layer having a surface that is hydrophobic and
a plurality of copper structures embedded in the foamed material layer.

43. (New) An conductive system comprising:
a substrate;
a foamed material layer on the substrate, the foamed material layer having a surface that is hydrophobic and a cell size of less than about one micron; and
a plurality of aluminum structures embedded in the foamed material layer.

44. (New) An integrated circuit structure comprising:
a substrate;
a plurality of stacked foamed polymer layers on the substrate, each of the stacked foamed polymer layers has a surface that is hydrophobic, and each of the foamed polymer layers has a cell size less than about one micron; and
a plurality of tungsten structures embedded in each of the plurality of foamed polymer

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